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## NEWS RELEASE

### **FlexFrame™ Adapters Offer Low Cost IC Obsolescence Solutions**

IC obsolescence issues are becoming an increasing burden for manufactures with long product life cycles. Today, many of the ICs going obsolete are in SMT gullwing and j-lead packages such as QFPs, PLCCs, TSOPs, and SOICs. ISI has developed a new interconnect system, FlexFrame™ to enable footprint conversion adapters that replace this family of packages.

FlexFrame™ consists of PhosBronze pins which are loaded into a FR4 carrier and bent to shape to emulate the gullwing or j-leads on the IC package. The FlexFrame™ connector is soldered between the adapter and host PCB to create a rugged, reliable interconnect.

FlexFrame™ is named for it's flexible configuration options including unique pin location and pitch, various standoff heights, and windows in the carrier that allow components to be placed in the center of the interconnect on the bottom of the adapter.

"IC obsolescence is a growing issue with our customer base, and we are currently designing 2 to 3 new products each week," says ISI Vice President, Mark Gilliam. "Our focus is on cost-effective solutions that can be utilized in ongoing production. Our modules and adapters have been qualified for use in high reliability applications including Military, Aerospace, Telecom, Networking, Server and Industrial markets", says Gilliam.

For production programs, ISI obsolescence adapters are typically priced \$1.00 to \$20.00 plus components, depending on complexity and volume. For more information go to [www.isipkg.com](http://www.isipkg.com) .

